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As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: Methods of Removing at Least Some of a Material from a Semiconductor Substrate, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

## PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so

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1	made are punishable	by fine or imprisonment, or both, under
2	Section 1001 of Title 18	of the United States Code and that such willful
3	false statement may jeo	pardize the validity of the application or any
4	patent issued therefrom.	
5	* * * * * * *	
6	Full name of inventor: Kevin J. Torek	
7	Inventor's Signature:	
8	Date:	
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11	rost office riddress.	718 N. Kastle Falls Ave.
12		leridian, ID 83642
13	k	* * * * * * * *
14	Full name of inventor: G	aro J. Derderian
15	Inventor's Signature:	
16	Date:	
17	Residence: Be	oise, ID
18	Citizenship: Us	5
19	TI CONTRACTOR OF THE CONTRACTO	84 S. Schooner Place
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